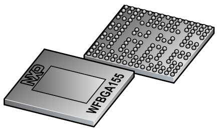


SOT1456-2

plastic very-very-thin fine-pitch ball grid array package; 155 balls, 0.5 mm pitch, 7.5 mm x 7.5 mm x 0.62 mm body

6 July 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WFBGA155
Package style descriptive code	WFBGA (very-very-thin profile fine-pitch ball grid array package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-06-2020
Manufacturer package code	98ASA01265D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.4	7.5	7.6	mm
package width	7.4	7.5	7.6	mm
package height	-	0.62	0.655	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	155	-	

2 Package outline

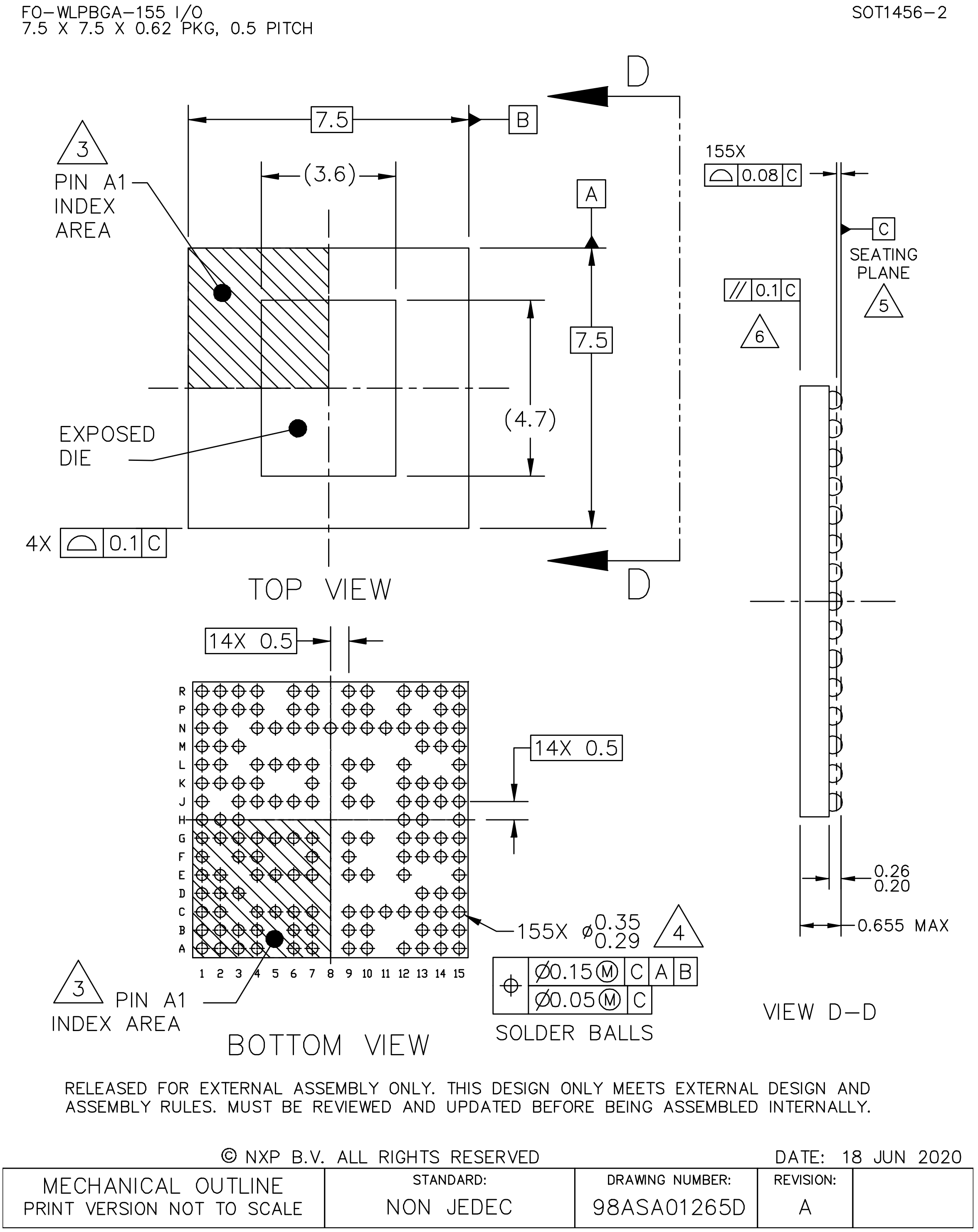
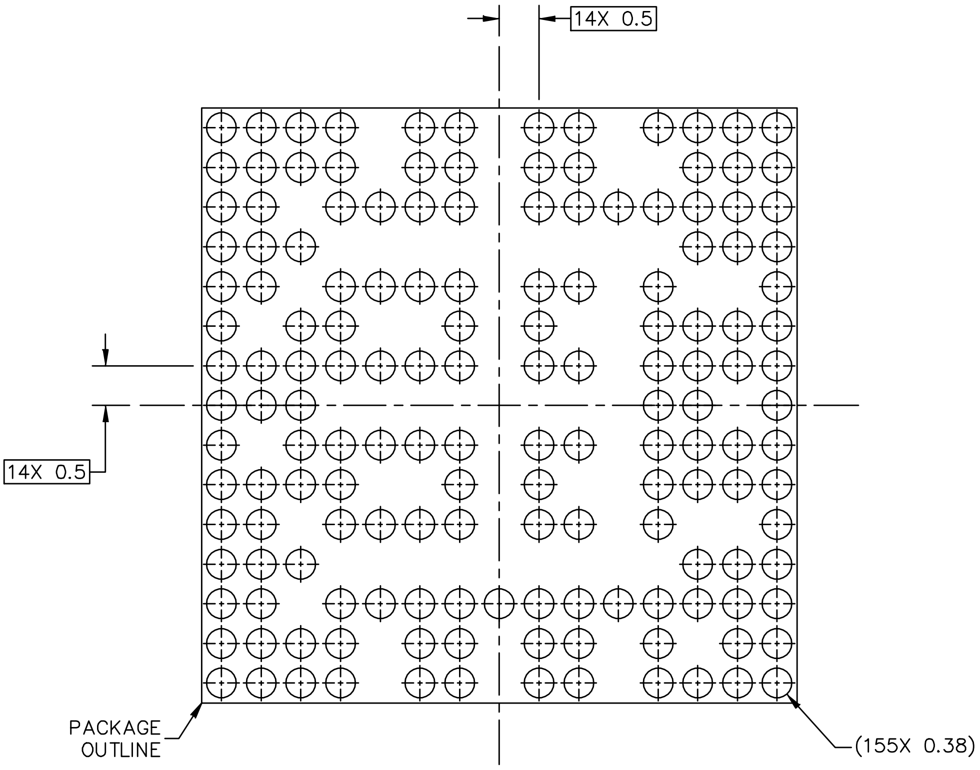


Figure 1. Package outline WFBGA155 (SOT1456-2)

3 Soldering

FO-WLPBGA-155 I/O
7.5 X 7.5 X 0.62 PKG, 0.5 PITCH

SOT1456-2



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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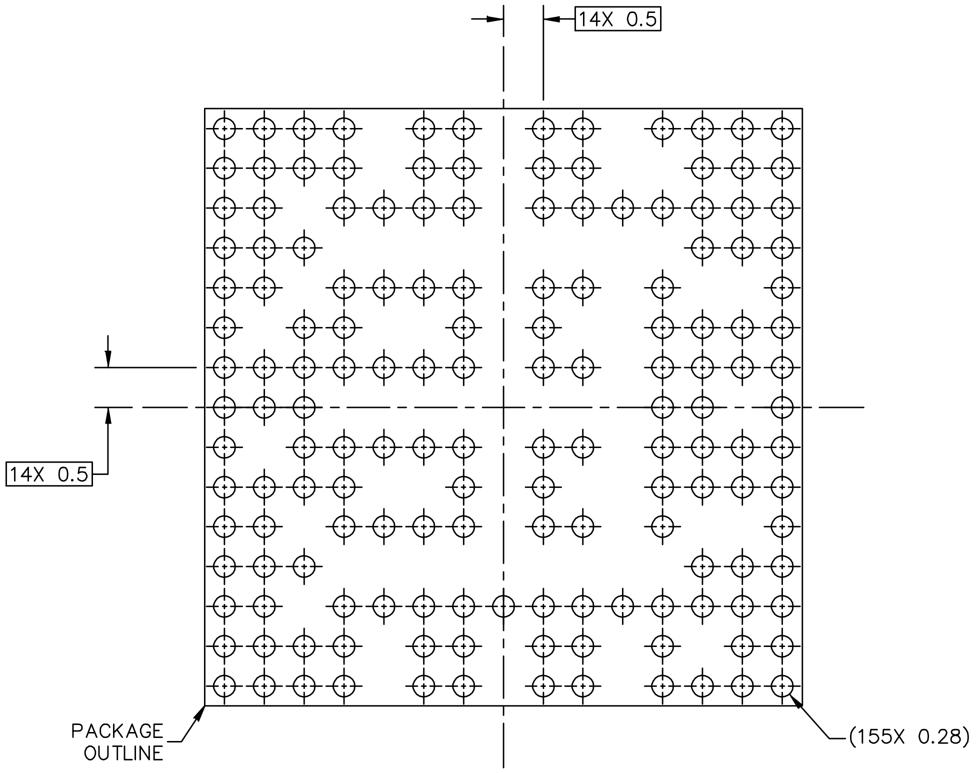
DATE: 18 JUN 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01265D	REVISION: A	

Figure 2. Reflow soldering footprint part1 for WFBGA155 (SOT1456-2)

FO-WLPBGA-155 I/O
7.5 X 7.5 X 0.62 PKG, 0.5 PITCH

SOT1456-2



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

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DATE: 18 JUN 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01265D	REVISION: A	

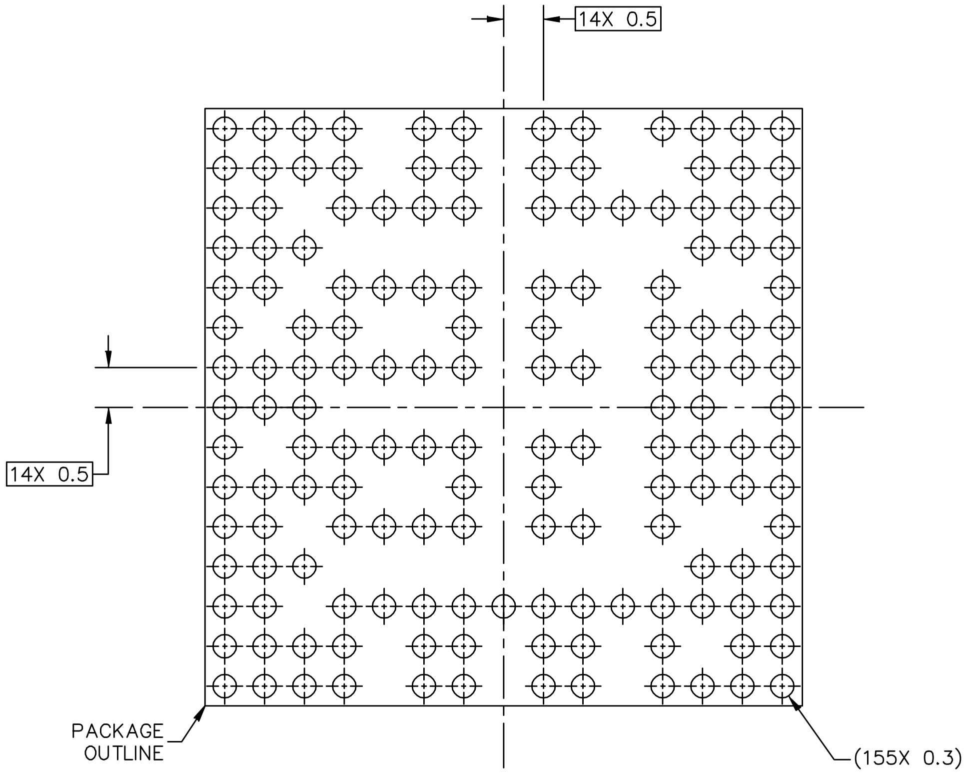
Figure 3. Reflow soldering footprint part2 for WFBGA155 (SOT1456-2)

SOT1456-2

plastic very-very-thin fine-pitch ball grid array package; 155 balls, 0.5 mm pitch, 7.5 mm x 7.5 mm x 0.62 mm body

FO-WLPBGA-155 I/O
7.5 X 7.5 X 0.62 PKG, 0.5 PITCH

SOT1456-2



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 18 JUN 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01265D	REVISION: A	

Figure 4. Reflow soldering footprint part3 for WFBGA155 (SOT1456-2)

FO–WLPBGA–155 I/O
7.5 X 7.5 X 0.62 PKG, 0.5 PITCH

SOT1456–2

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

DATE: 18 JUN 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01265D	REVISION: A	

Figure 5. Package outline note WFBGA155 (SOT1456-2)

4 Legal information

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